

Image 2858



PATENT  
YO996-184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : D.Y.Shih, et al.  
Serial Number : 09/254,769  
Filing Date : March 11, 1999  
Examiner : V. Nguyen  
Group Art Unit : 2858  
For : WAFER SCALE HIGH DENSITY  
PROBE ASSEMBLY ,  
APPARATUS FOR USE THEREOF  
AND METHODS OF  
FABRICATION THEREOF

Honorable Commissioner of Patents  
and Trademarks  
Post Office Box 1450  
Alexandria, VA 22313-1450

Sir:

In response to the Official Action dated January 5, 2004, please consider the following remarks with respect to the above-identified application as follows:

**REMARKS**

The present invention relates to a method for making an inter-connector to couple an electric module to a circuit board. The invention provides a probe structure that is an integral part of the fan-out wiring on the test substrate or other printed wiring means to minimize the electrical conductor length as well as contact resistance of the probe interface. The probe is provided with a compliant interface to compensate for slight variations in the rigid bond pad heights on the IC device and variations in the height of the probe contacts.